CLAIMS

1. A processing system comprising:

a plurality of types of internal processing machines that perform various processes on a substrate; and

an interface section that delivers and receives said substrate to and from an external processing machine for performing a specific process on said substrate, wherein

said interface section includes:

a transfer unit for taking in said substrate from at least one of said internal processing machines and transferring the substrate to said external processing machine; and

a substrate table unit arranged adjacent to the external processing machine for temporarily holding said substrate in transferring said substrate between said internal processing machine and said ~~external processing machine~~ interface section via said transfer unit, and

said substrate table unit has first and second tables that are laid one on top of the other and can move up and down and stop at a specific height, said first table allowing said substrate to be temporarily placed on it in transferring said substrate to said external processing machine, said second table allowing said substrate to be temporarily placed on it in receiving said substrate from said external processing machine, and said transfer unit transferring said

a plurality of types of internal processing machines including at least one photoresist coating machine that perform at least a photoresist coating process on a semiconductor substrate; and

an interface section that delivers and receives said semiconductor substrate to and from an external exposure machine for performing an exposure process on said substrate subjected to the photoresist coating process, wherein

said interface section includes:

a transfer unit for taking in said substrate from said photoresist coating machine and transferring the substrate to said external exposure machine; and

a substrate table unit adjacent to the external exposure machine for temporarily holding said substrate in transferring said substrate between said ~~photoresist coating machine~~ interface section and said external exposure machine via said transfer unit, and

said substrate table unit has first and second tables that are laid one on top of the other and can move up and down and stop at a specific height, said first table allowing said substrate to be temporarily placed on it in transferring said substrate to said external exposure machine, said second table allowing said substrate to be temporarily placed on it in receiving said substrate from said external exposure machine, and said transfer unit transferring said substrate between each of said first and second tables

the center of said support base, with said substrate being supported by said support pins in the vicinity of said substrate's center and the periphery being supported by said periphery support sections.

18. A processing system according to claim 12, wherein said first table is located at the upper stage and said second table is located at the lower stage.

19. A processing system, substantially as hereinbefore described with reference to the accompanying drawings.

New claims 19-26 attached.

19. A processing system comprising:

a plurality of types of internal processing machines that perform various processes on a substrate; and

an interface section that delivers and receives said substrate to and from an external processing machine for performing a specific process on said substrate, wherein

said interface section includes:

a transfer unit for taking in said substrate from at least one of said internal processing machines and transferring the substrate to said external processing machine; and

a substrate table unit arranged adjacent to said external processing machine for temporarily holding said substrate in transferring said substrate between said interface section and said external processing machine via said transfer unit, and

said substrate table unit has first and second tables that are laid one on top of the other and can move up and down and stop at a specific height, each of said first table and said second table having two placement tables side by side to allow two substrates to be temporarily placed on them in transferring a substrate between said external processing machine and said interface section, and said transfer unit transferring said substrate between said first and second tables and at least one of said internal processing machines.

20. A processing system according to claim 19, wherein said transfer unit can rotate freely and access said processing machine arbitrarily.

21. A processing system according to claim 19, wherein said transfer unit can access the two placement tables of each of said first table and said second table obliquely.

22. A processing system according to claim 19, wherein each of said first table and said second table includes an up-and-down support member that moves up and down, a support base part of which is stuck to the up-and-down support member, a plurality of periphery support sections that are provided on the support base and support the periphery of said substrate, and a plurality of support pins provided in the vicinity of the center of said support base, with said substrate being supported by said support pins in the vicinity of a center of said substrate and the periphery being supported by said periphery support sections.

23. A processing system according to claim 19, wherein said first table is located at the upper stage and said second table is located at the lower stage.

24. A processing system according to claim 19, wherein said first placement table allows the substrate unloaded from said external processing machine to be temporarily placed on it and said second placement table allows the substrate loaded into said external processing machine to be temporarily placed on it.

25. A processing system according to claim 1, wherein said substrate table unit can stop at a specific height corresponding to a wafer delivery position of said external processing machine.

26. A processing system according to claim 12, wherein said substrate table unit can stop at a specific height corresponding to a wafer delivery position of said external machine.

ABSTRACT OF THE DISCLOSURE (FIG. 2)

"PROCESSING SYSTEM"

A processing system comprises a plurality of types of internal processing machines (COT, DEV) that perform various processes on a semiconductor substrate and an interface section (13) that delivers and receives the semiconductor substrate to and from an external exposure machine (12) for performing an exposure process on the substrate subjected to a resist coating process, wherein the interface section includes a transfer unit (32) for taking in the substrate subjected to a specific process from at least one of the internal processing machines and transferring the substrate and a substrate table unit (33) for temporarily holding the substrate to transfer the substrate between the internal processing machine and the external exposure machine via the transfer unit. The substrate table unit has a first and second tables that are laid one on top of the other and can move up and down and stop at a specific height, the first table allowing the substrate to be temporarily placed on it in transferring the substrate to the external exposure machine, and the second table allowing the substrate to be temporarily placed on it in receiving the substrate from the external exposure machine. The transfer unit transfers the substrate between the first and second tables and at least one of the processing machines.